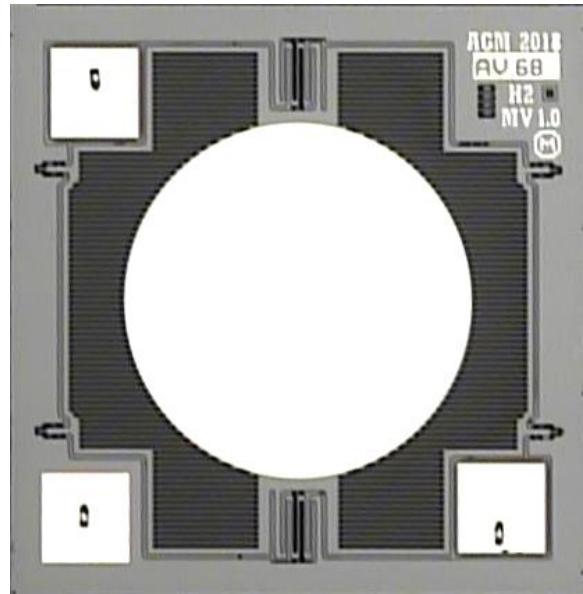




## MiniVOA / MiniTF MEMS chip

The AGM MiniVOA / MiniTF family of products are one axis micromirror chips that can be actuated in both positive (clockwise) and negative (counterclockwise) directions. These chips feature small size coupled with high functionality. The angular rotation of up to 2.5° allow these chips to find use in a wide range of applications, while the miniature footprint allows them to be deployed in challenging environments where space and packaging requirements are extremely tight. Performance specifications are given below.



### Part Numbers:

MiniVOA/TF (standard) chip:  
 AGM Part Number 786061  
 MiniVOA/TF 5.4V chip:  
 AGM Part Number 786062  
 Protected by US Patent Nos.  
 7,863,799 and 7,986,073

### Key Specifications:

Item	Parameter	Conditions	Value			Unit	Certification
			Min	Typ	Max		
1.	Excess Insertion Loss	Excess Insertion Loss of chip relative to perfect mirror			0.25	dB	5 chips per wafer
2.	Chip Dimension	Length			1.0	mm	By Design
		Width			1.0	mm	
		Thickness	0.43	0.44	0.45	mm	
3.	Operating temperature		-20		85	°C	Customer Qual.



## MiniVOA / TF MEMS line of Products

4.	Reflectivity (Al mirror)	S, C, L band	95			%	Foundry Production
5.	Mirror curvature		-0.5	0	2.00	m <sup>-1</sup>	Foundry Qual.
6.	Mirror diameter		600			um	By Design
7.	Voltage at 2.5° rotation	In positive & negative directions	11.5		16	V	100 %
8.	Snap Margin	Voltage margin above the 2.5° voltage	10			%	5 chips per wafer
9.	Resistance	Between Drive & Ground bondpads	200			MΩ	100 %
10.	Bondpad size	Square shape	150			um	By Design